



12-28-2007



103471594

PATENTS ONLY

Docket No.: 062758-0197

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Hiroyuki KAMIYAMA, Masaru MUKAIKUBO, Hiroaki
INOUE, Chiyuki KITAHARAAdditional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): December 14, 2007, December 10, 2007,
December 10, 2007, December 17, 2007
(respectively)

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: OPNEXT JAPAN, INC.

Internal Address:

Address: 216, Totsuka-cho, Totsuka-ku, Yokohama-shi,
Kanagawa 244-8567 JAPANAdditional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application or patent number(s):

A. Patent Application No(s). 11/882,595 filed on August 2, 2007

☐ This document is being filed together with a new application.

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

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Fax Number: 202.756.8087

Email Address:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

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9. Signature.

Keith George 34,111

December 21, 2007

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents 2

ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Opnext Japan, Inc., a corporation organized under the laws of Japan, located at 216, Totsuka-cho, Totsuka-ku, Yokohama-shi, Kanagawa, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Opnext Japan, Inc., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

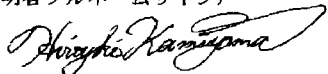

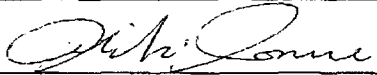

**METHOD OF MANUFACTURING SEMICONDUCTOR LASER
FOR COMMUNICATION, SEMICONDUCTOR LASER FOR
COMMUNICATION AND OPTICAL TRANSMISSION MODULE**

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Opnext Japan, Inc., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Opnext Japan, Inc.

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	 Hiroyuki KAMIYAMA	Dec. 14, 2007
2)	 Masaru MUKAIKUBO	Dec. 10, 2007
3)	 Hiroaki INOUE	Dec. 10, 2007
4)	 Chiyuki KITAHARA	Dec. 17, 2007
5)		
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